



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



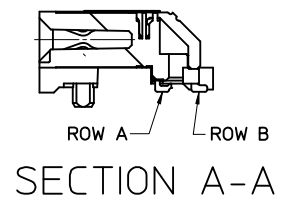
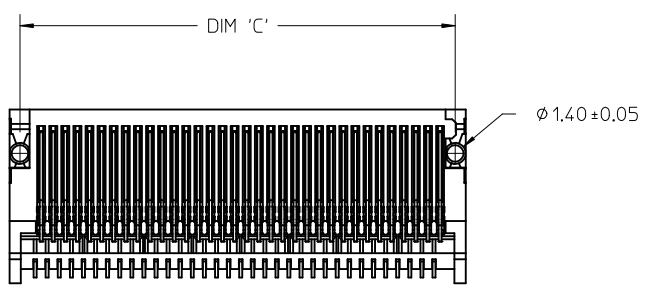
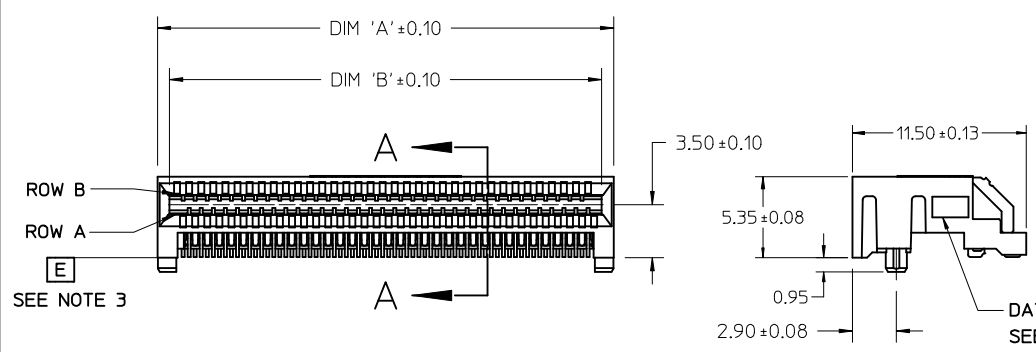
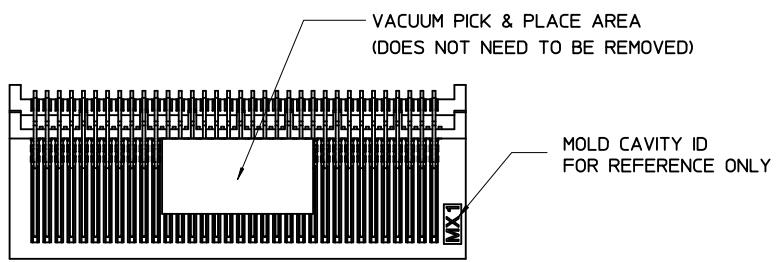
Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

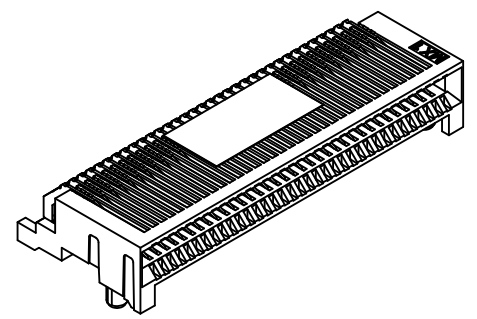
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





68 CIRCUIT ASSEMBLY SHOWN

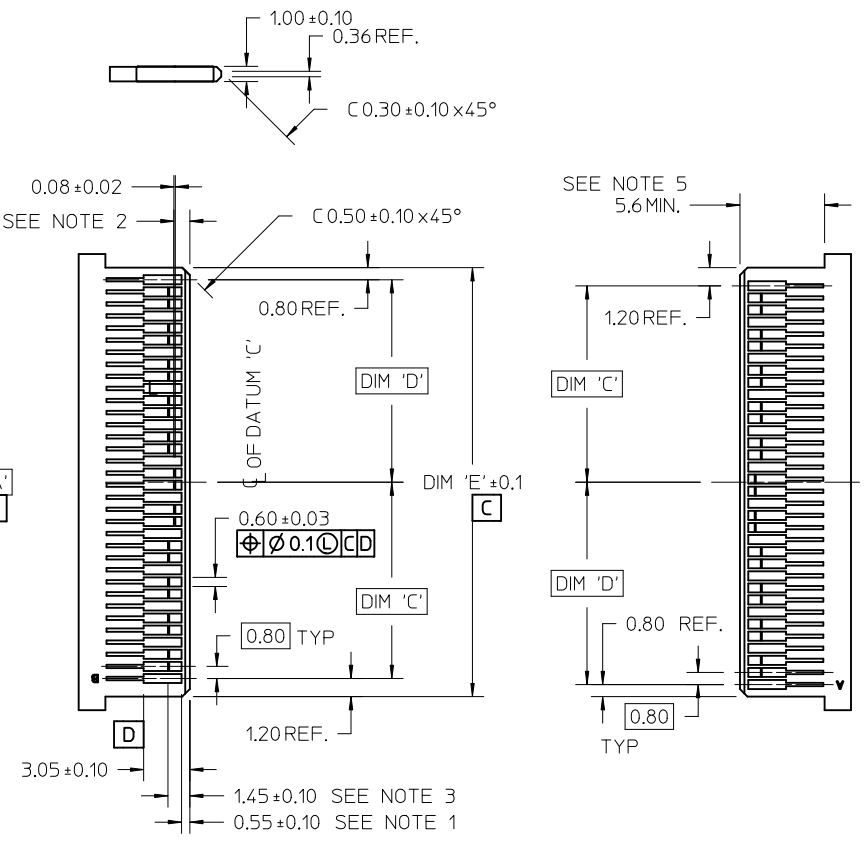
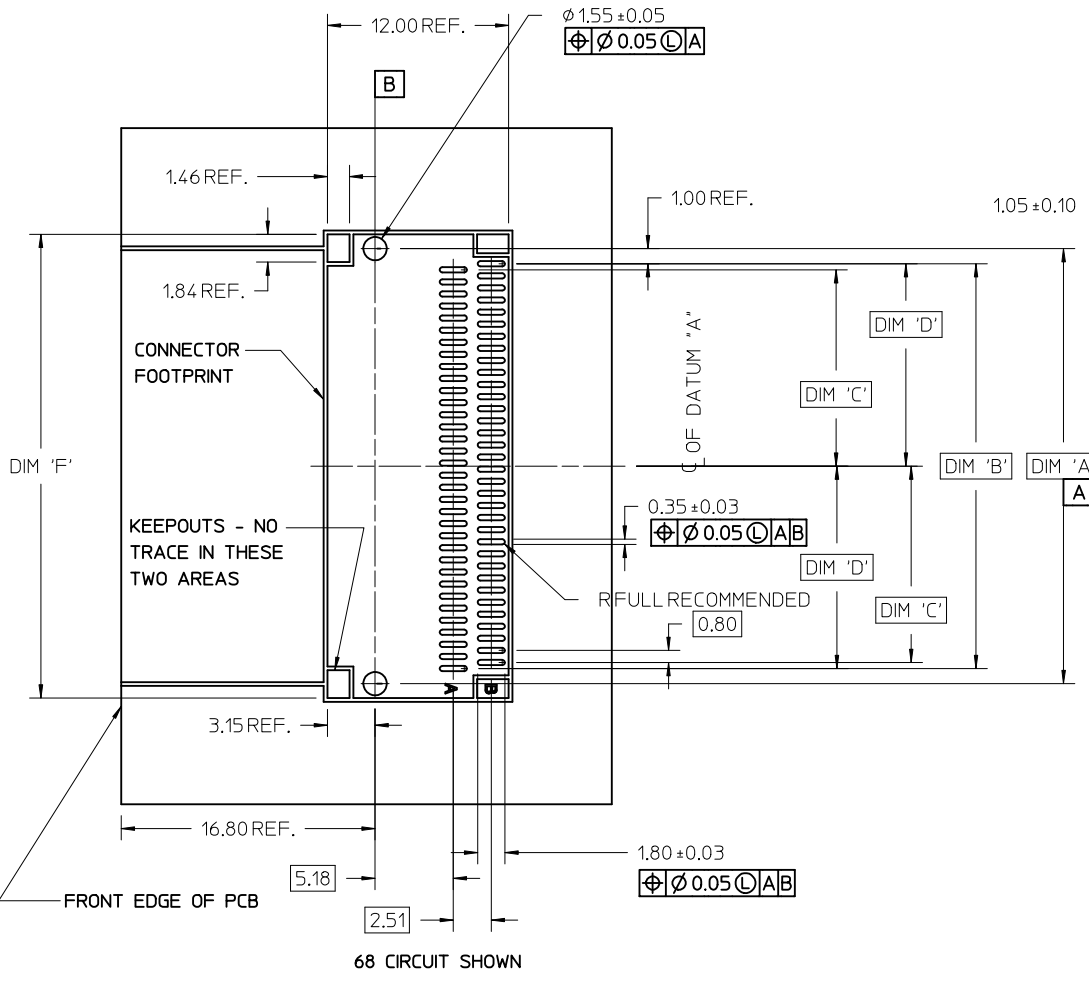


CIRCUIT SIZE	ITEM NUMBER	PLATING OPTION	DIM 'A'	DIM 'B'	DIM 'C'
26	75586-0004	OPTION 1	13.40	11.80	12.00
26	75586-0009	OPTION 2	13.40	11.80	12.00
36	75586-0003	OPTION 1	17.40	15.80	16.00
36	75586-0008	OPTION 2	17.40	15.80	16.00
38	75586-0010	OPTION 1	18.20	16.60	16.80
38	75586-0011	OPTION 2	18.20	16.60	16.80
50	75586-0001	OPTION 1	23.00	21.40	21.60
50	75586-0006	OPTION 2	23.00	21.40	21.60
68	75586-0002	OPTION 1	30.20	28.60	28.80
68	75586-0007	OPTION 2	30.20	28.60	28.80

- NOTES
- MATERIAL:
HOUSING - HIGH TEMPERATURE THERMOPLASTIC GLASS FILLED, UL 94V-0, BLACK
TERMINALS - COPPER ALLOY
 - PLATING:
OPTION 1
CONTACT AREA - 0.38 μm MIN GOLD OVER 2.54 μm MIN NICKEL
SOLDER FOOT AREA - 2.54 - 5.09 μm TIN OVER 1.27 μm MIN NICKEL.
OPTION 2
CONTACT AREA - 0.76 μm MIN GOLD OVER 2.54 μm NICKEL
SOLDER AREA - 2.54 - 5.09 μm TIN OVER 1.27 μm MIN NICKEL
 - TERMINAL SOLDER FEET TO BE COPLANAR WITHIN 0.10/004 MEASURED FROM FRONT HOUSING STAND OFF (DATUM E)
 - DATE CODE: 4 DIGIT (3 DIGIT DATE, 1 DIGIT YEAR)
 - CIRCUIT IDENTIFIER: SEE APPROPRIATE INDUSTRY SPECIFICATION FOR LOCATION OF PIN 1
 - TO BE USED WITH EXTERNAL CABLES (74546 & 74547 SERIES) AND GUIDE FRAMES (74540 & 74548 SERIES)
 - TESTER/ANALYZER CABLES AVAILABLE (74557 & 74558 SERIES)
 - PACKAGED PER PACKAGING SPECIFICATION: PK-75586-002
 - CONFORMS TO PRODUCT SPECIFICATION: PS-75586-001
 - THIS PART CONFORMS TO CLASS C REQUIREMENTS OF COSMETIC SPECIFICATION PS-45499-002.

iPass™ IS A TRADEMARK OF MOLEX

REVISED NOTE 2 IEC NO: UCP2012-4064 DRWN: TMCLELL 2012/06/26 CHKD: APPR: MBANAKIS 2012/06/28 REV: G2	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE 4:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	▽=0	mm INCH	DRAWN BY DATE KREGNIER 07/28/04	TITLE I-PASS R/A CONNECTOR EXTERNAL ASSEMBLY .8 MM PITCH I/O		
	▽=0	4 PLACES ± --- ± ---	CHECKED BY DATE JLONG 07/29/04	DOCUMENT NO. SD-75586-001		
	▽=0	3 PLACES ± --- ± ---	APPROVED BY DATE RNELSON 07/30/04	SHEET NO. 1 OF 3		
		0 PLACE ± ±	ANGULAR ±1/2°	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			



- NOTES:**
- PAD CONFIGURATION FOR FIRST MATE.
 - PAD CONFIGURATION FOR SECOND MATE.
 - PAD CONFIGURATION FOR THIRD MATE (HIGH SPEED SIGNALS).
 - FOR PIN ASSIGNMENTS AND MATING SEQUENCE (1ST, 2ND, 3RD), SEE APPLICABLE SPECIFICATION.
 - MINIMUM STEP REQUIRED IF PCB MADE WIDER THAN CARD TOUNGE.
 - SEE 74540 OR 74548 SERIES FOR GUIDE FRAME FOOT PRINT AND KEEP OUT AREA.

iPass™ IS A TRADEMARK OF MOLEX

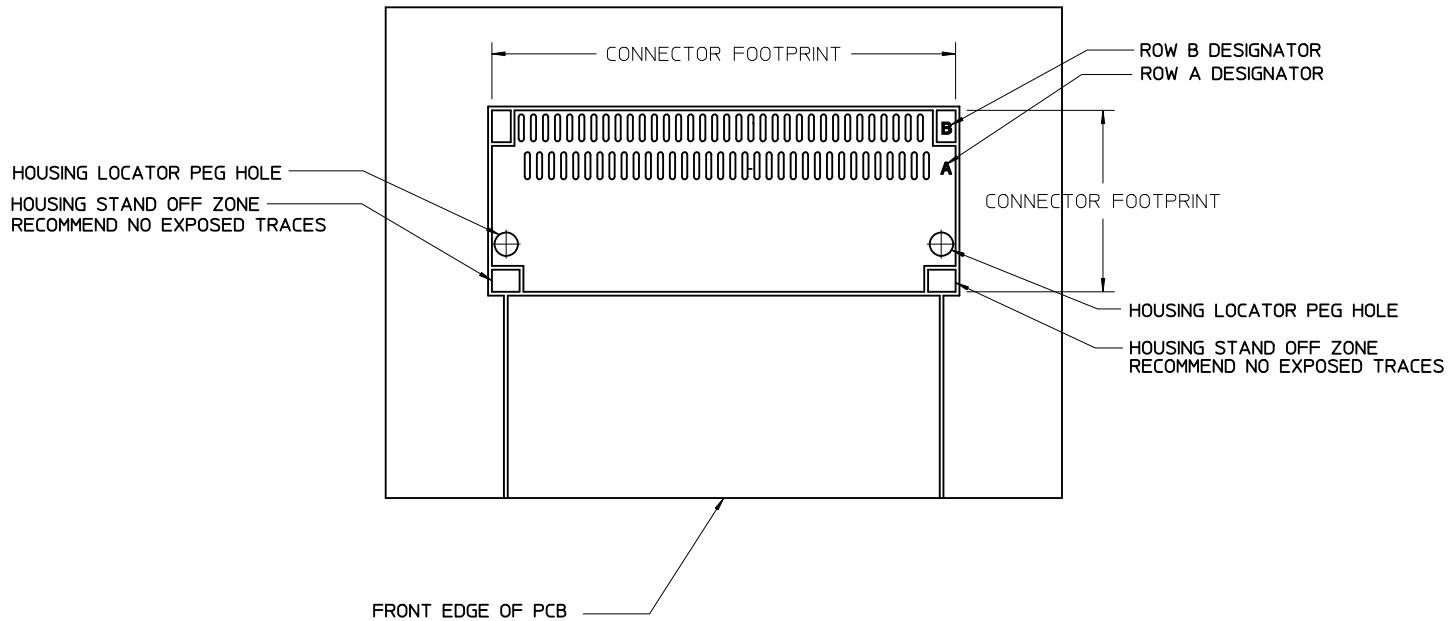
CIRCUIT SIZE	TERM/SIDE 'N'	DIM 'A'	DIM 'B'	DIM 'C'	DIM 'D'	DIM 'E'	DIM 'F'
26	13	12.00	10.00	4.60	5.00	11.60	13.90
36	18	16.00	14.00	6.60	7.00	15.60	17.90
38	19	16.80	14.80	7.00	7.40	16.40	18.70
50	25	21.60	19.60	9.40	9.80	21.20	23.50
68	34	28.80	26.80	13.00	13.40	28.40	30.70

SEE SHEET 1
 EC NO: UCP2012-4064
 DRWN:MCLELL 2012/06/26
 CHKD:
 APPR:MBANAKIS 2012/06/28
 REV: G2

QUALITY SYMBOLS
 GENERAL TOLERANCES (UNLESS SPECIFIED)
 4 PLACES ± --- ± ---
 3 PLACES ± --- ± ---
 2 PLACES ± 0.13 ± ---
 1 PLACE ± 0.25 ± ---
 0 PLACE ± ±
 ANGULAR ±1/2°
 DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE MM ONLY
 DRAWN BY DATE
 KREGNIER 07/28/04
 CHECKED BY DATE
 JLONG 07/29/04
 APPROVED BY DATE
 RNELSON 07/30/04
 MATERIAL NO.
 SEE CHART
 SIZE C

SCALE 4:1
 DESIGN UNITS METRIC
 THIRD ANGLE PROJECTION
 I-PASS R/A CONNECTOR EXTERNAL ASSEMBLY .8 MM PITCH I/O
molex
 DOCUMENT NO. SD-75586-001
 SHEET NO. 2 OF 3
 THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION



iPass™ IS A TRADEMARK OF MOLEX

SEE SHEET 1 EC NO: UCP2012-4064 DRWN:TMCCLELL 2012/06/26 CHKD: APPR:MBANAKIS 2012/06/28	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0	mm INCH	MM ONLY	4:1	METRIC	
	▽=0	4 PLACES ± --- ± ---	DRAWN BY DATE	TITLE I-PASS R/A CONNECTOR EXTERNAL ASSEMBLY .8 MM PITCH I/O molex		
	▽=0	3 PLACES ± --- ± ---	KREGNIER 07/28/04			
REV	DESCRIPTION	ANGULAR ±1/2°	CHECKED BY DATE	DOCUMENT NO. SD-75586-001 SHEET NO. 3 OF 3		
G2		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	JLONG 07/29/04			
			APPROVED BY DATE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
			RNELSON 07/30/04			